

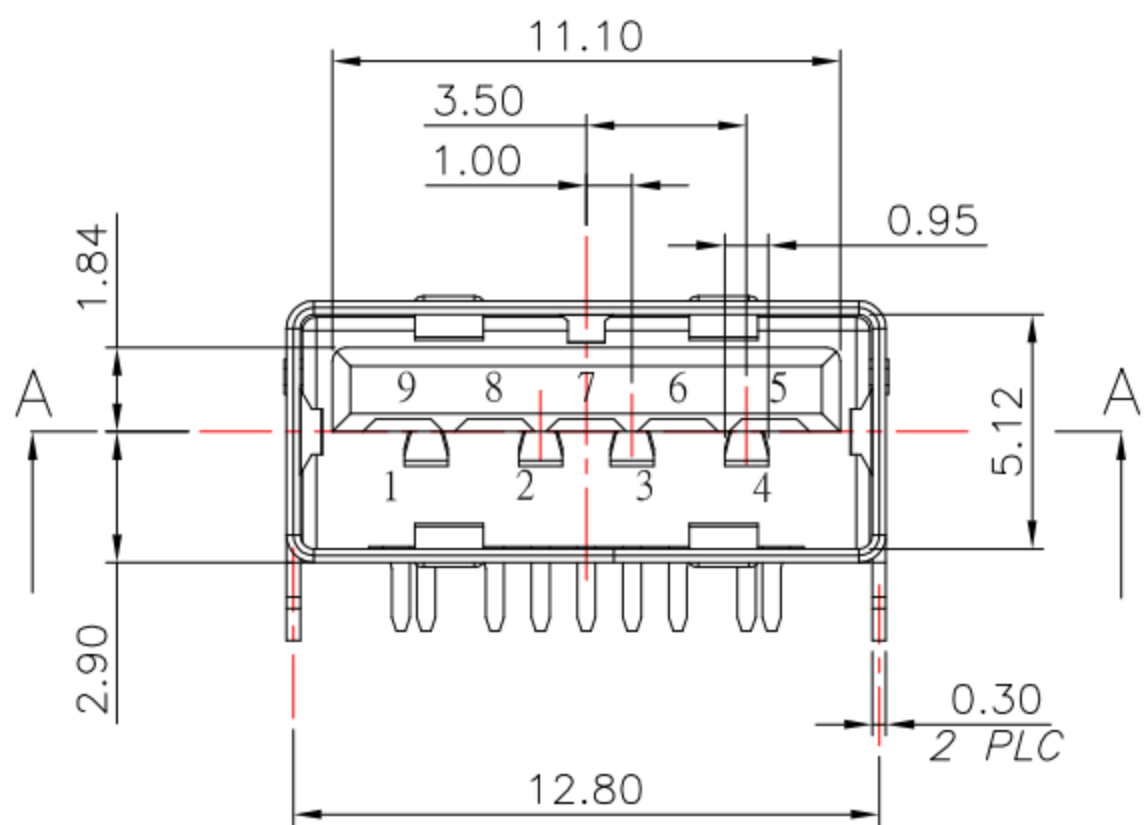
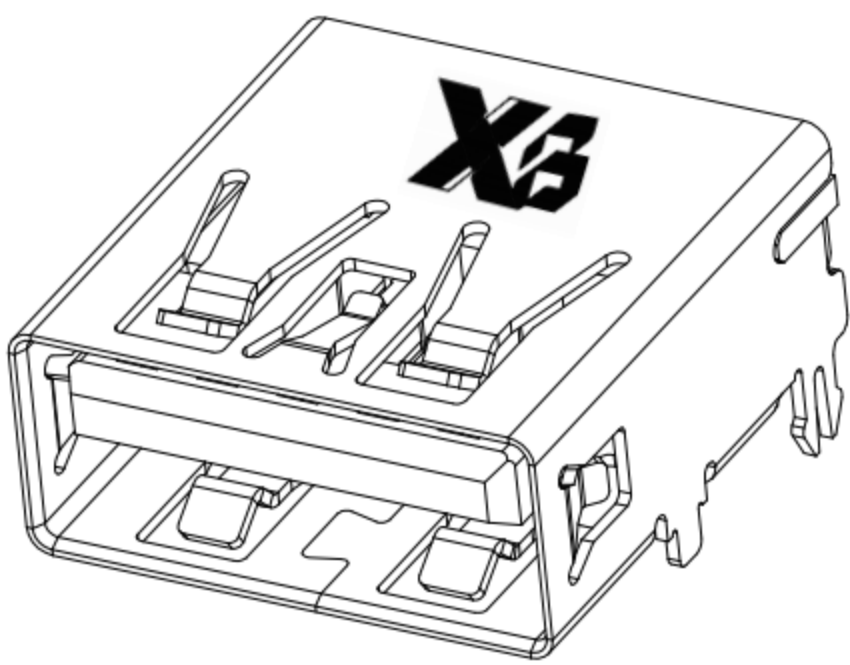
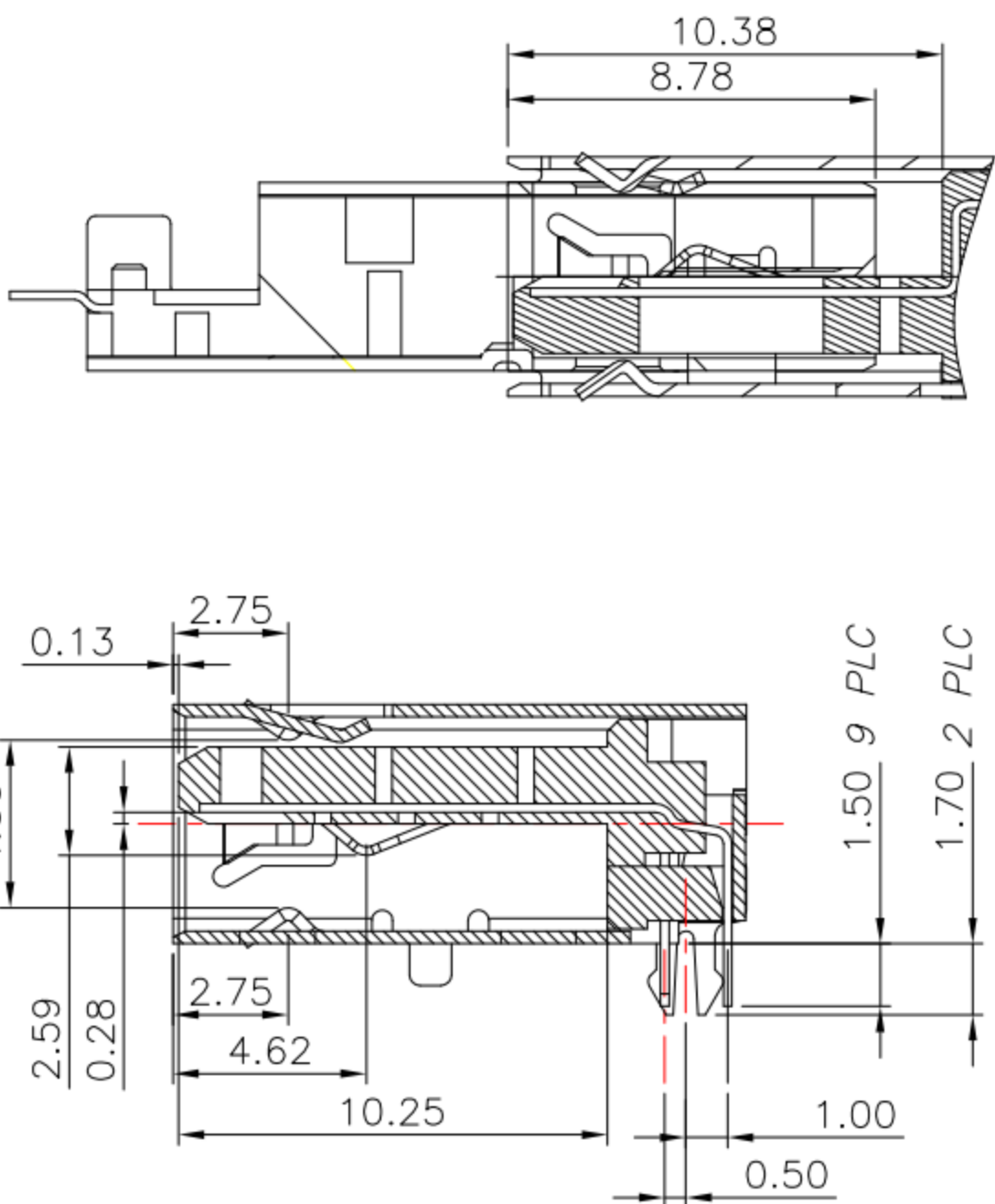
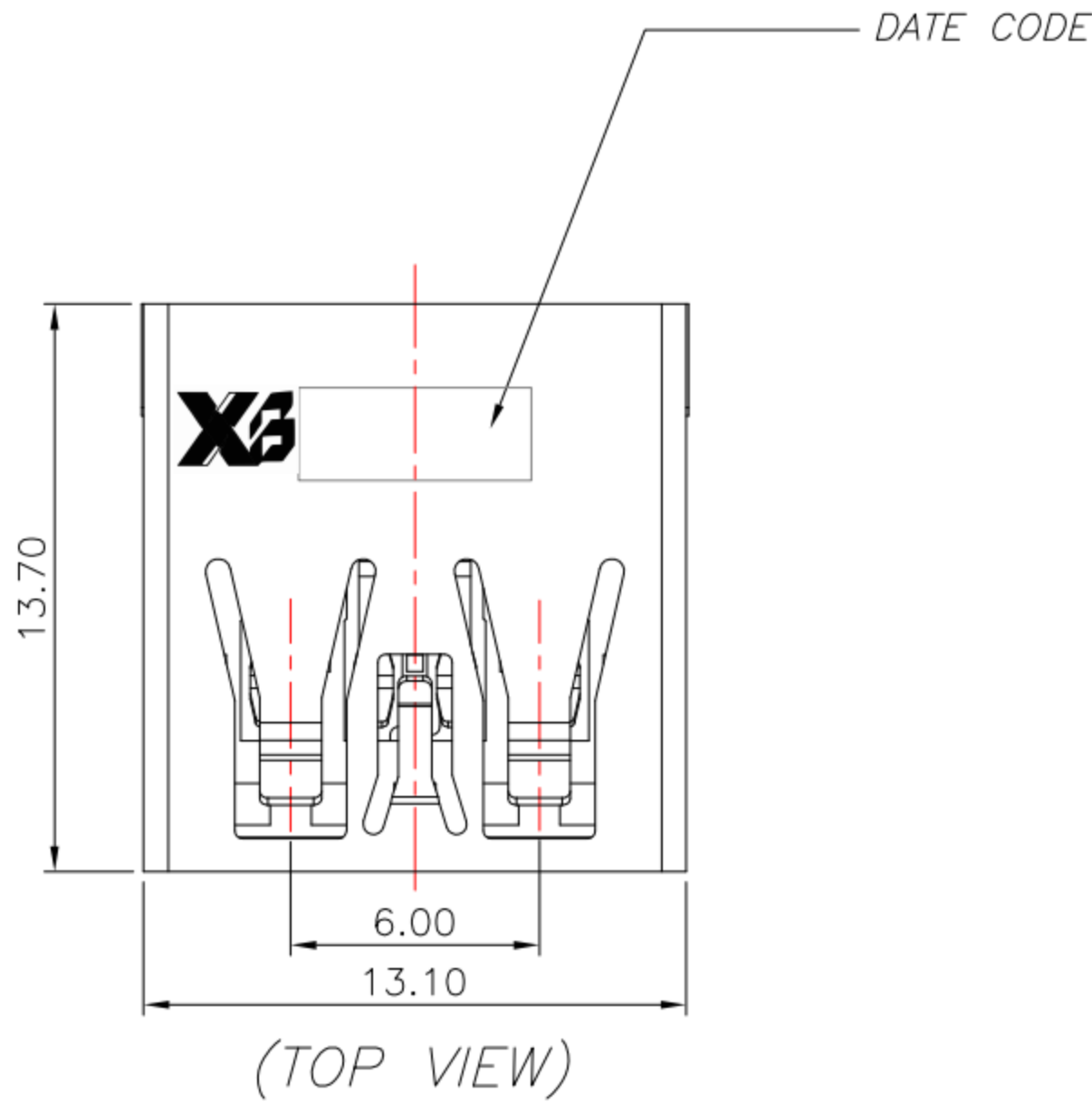


SUA-110H24-30xx-S277

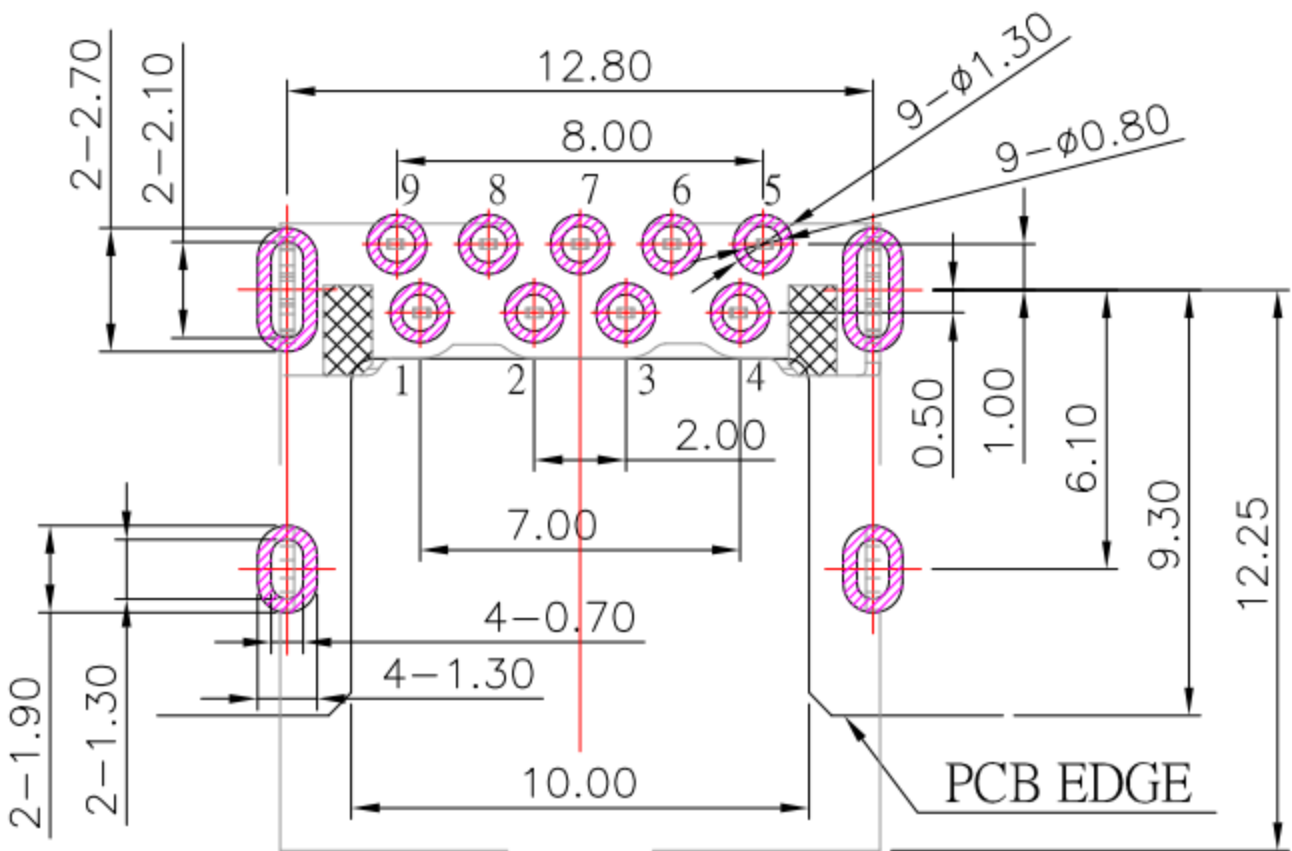
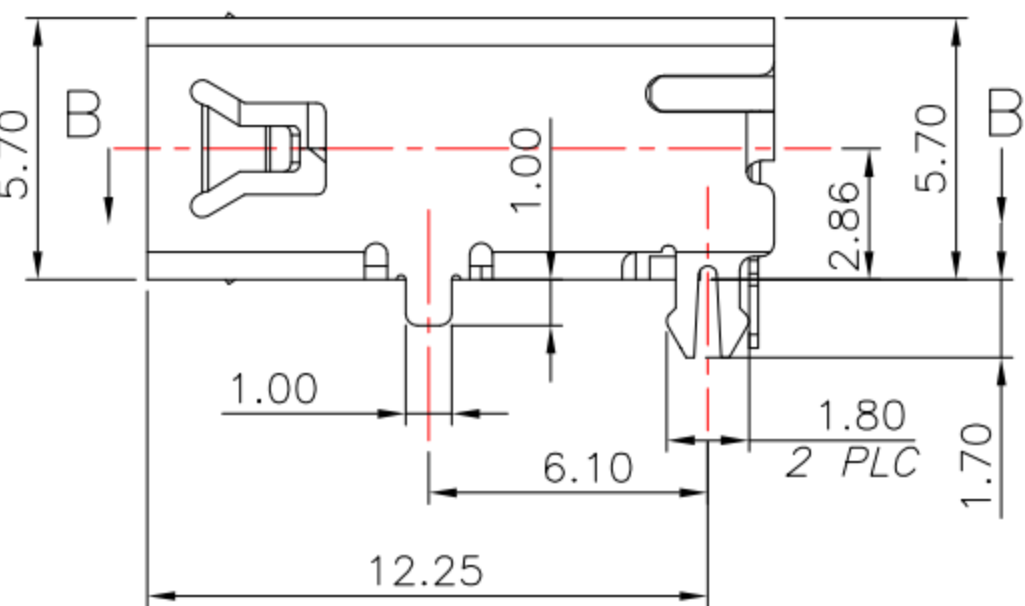
鍍層厚度：	COLOR：
Blank：1u"	BLUE：Blank
2：15u"	Black：B
3：30u"	Red：R

NOTE:

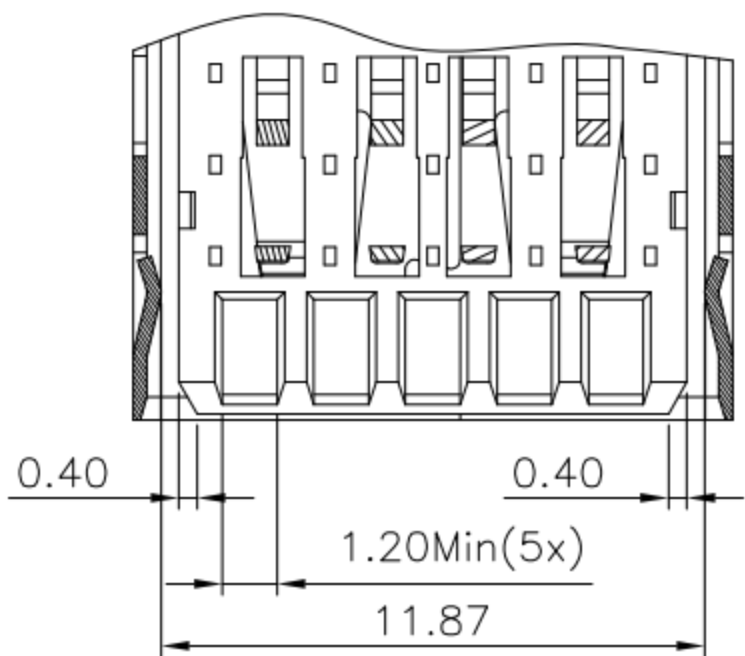
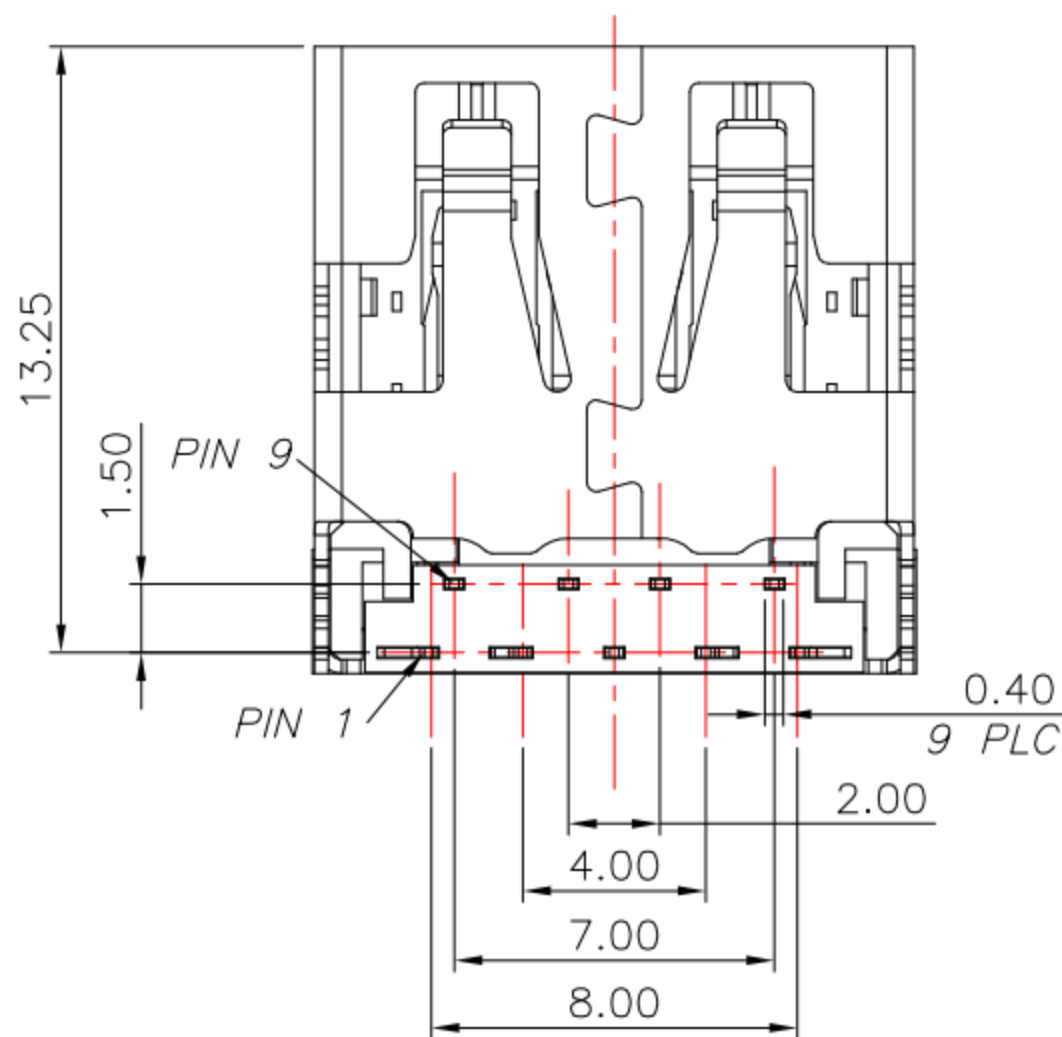
- 1.MATERIAL:
- 1.1 Housing: LCP,(UL94V-0)
- 1.2 Contact: Phosphor Bronze
- 1.3 Shell: SUS
- 2.Finish:
- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer
- 3.SPECIFICATION:
- 3.1 Current Rate: 1.5 A
- 3.2 insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 500V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -40℃ ~ +85℃
- 3.6 Insertion Force: 35 N
- 3.7 Extraction Force: 10 N



SECTION B-B



RECOMMENDED PCB LAYOUT
(TOP VIEW)



SECTION A-A

Pin #	SIGNAL NAME	DESCRIPTION	MATING SEQUENCE
1	VBUS	POWER	SECOND
2	D-	USB 2.0 DIFFERENTIAL PAIR	THIRD
3	D+		
4	GND	GROUND FOR POWER RETURN	SECOND
5	StdA_SSRX-	SUPERSPEED RECEIVER DIFFERENTIAL PAIR	LAST
6	StdA_SSRX+		
7	GND_DRAIN	GROUND FOR SIGNAL RETURN	
8	StdA_SSTX-	SUPERSPEED TRANSMITTER DIFFERENTIAL PAIR	
9	StdA_SSTX+		
Shell	Shield	CONNECTOR METAL SHELL	FRIST

5	更新pcb layout	Jack	030520
4	新增pcb layout尺寸	Jack	101619
3	更新pcb layout	Jack	092618
2	更新為A0版	Jack	051617
1	更新尺寸6.6改6.1	Jack	040715
ITEM NO.	DESCRIPTION	DRAWN	DATE



TOLERANCE UNLESS OTHERWISE STATED :	Up to 5 ±0.2 Above 5 ~ 15 ±0.3 Above 15 ~ 30 ±0.4 Above 30 ~ 50 ±0.5 Angle ±0.3°	3RD. ANGEL'S	UNITS	MM
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DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	03/05/20	FINISH	MODLE	USB A/F DIP R/A TYPE
CHECKED BY:	DATE	SCALE	DWG NO.	SUA-110H24-30xx-S277
Jacky Chen	03/05/20	1 : 1	PART NO.	SUA-110H24-30xx-S277
APPROVED BY:	DATE	SHEET NO.	1 of 1	SIZE A4
Tony Kao	03/05/20			VER R5